

ABSTRACT

Provided is a back surface protective film-forming composite (1) including a protection layer (12) and a back surface protective film-forming film (13), which are laminated. The composite (1) is used in a method of manufacturing a first laminate, the method including: a first lamination step of affixing the back surface protective film-forming film (13) to a back surface of a semiconductor substrate to obtain a second laminate including the semiconductor substrate, the back surface protective film-forming film (13), and the protection layer (12), which are laminated in this order; curing the back surface protective film-forming film (13) of the second laminate to form a back surface protective film; and conveying the second laminate from the first lamination step to the curing step, and wherein the first laminate includes the semiconductor substrate, the back surface protective film, and the protection layer (12), which are laminated in this order.

FIG. 2